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(12) United States Design Patent

Sharma et al.

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(54) **ARRAY OF TRIANGULAR SEMICONDUCTOR DIES**

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(73) Assignee: **Soraa, Inc.**, Fremont, CA (US)

(**) Term: **14 Years**

(21) Appl. No.: **29/441,116**

(22) Filed: **Dec. 31, 2012**

Related U.S. Application Data

(63) Continuation of application No. 13/357,578, filed on Jan. 24, 2012, which is a continuation-in-part of application No. 13/163,482, filed on Jun. 17, 2011, now Pat. No. 8,293,551.

(51) **LOC (10) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
USPC D13/110, 182, 184; 361/679.01, 728, 361/761, 820, 718, 764, 748, 752, 783; 257/668, 678, 684; 324/71.5, 252; 29/825, 829, 830, 831, 832, 846; 174/68.1, 250–261, 268; 216/13; 428/901
See application file for complete search history.

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(57) **CLAIM**

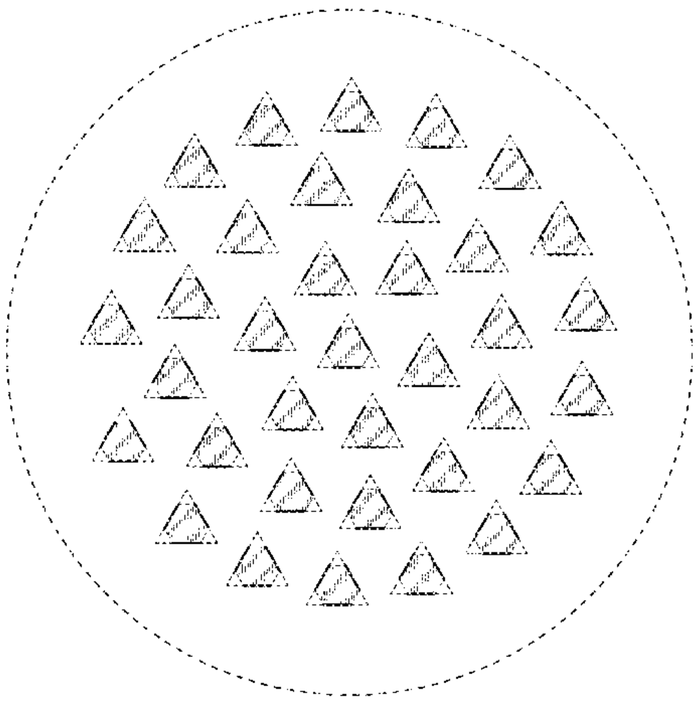
The ornamental design for an array of triangular semiconductor dies, as shown and described.

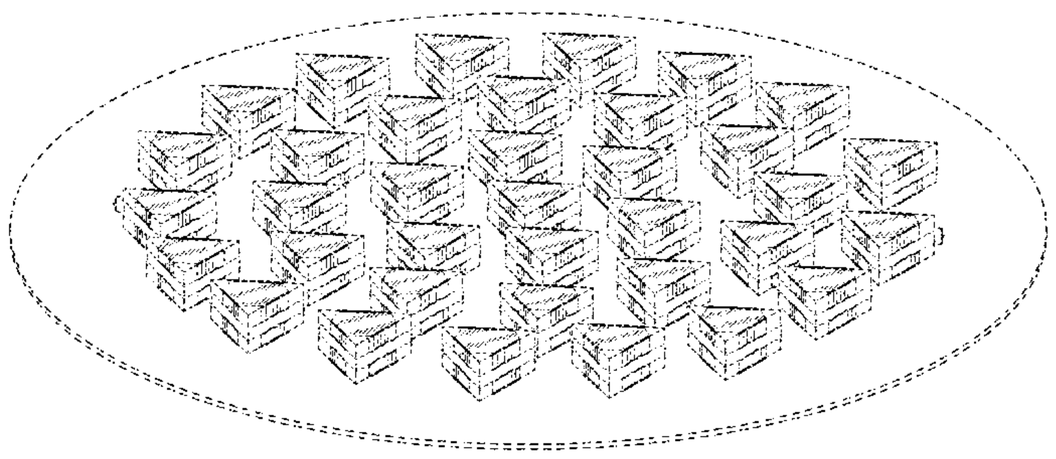
DESCRIPTION

FIG. **1** is a top plan view of a first embodiment of an array of triangular semiconductor dies showing our new design;
FIG. **2** is a front perspective view thereof;
FIG. **3** is a rear perspective view thereof;
FIG. **4** is a top plan view of a second embodiment of an array of triangular semiconductor dies showing our new design;
FIG. **5** is a front perspective view thereof;
FIG. **6** is a rear perspective view thereof;
FIG. **7** is a top plan view of a third embodiment of an array of triangular semiconductor dies showing our new design;
FIG. **8** is a front perspective view thereof;
FIG. **9** is a rear perspective view thereof;
FIG. **10** is a top plan view of a fourth embodiment of an array of triangular semiconductor dies showing our new design;
FIG. **11** is a front perspective view thereof;
FIG. **12** is a rear perspective view thereof;
FIG. **13** is a top plan view of a fifth embodiment of an array of triangular semiconductor dies showing our new design;
FIG. **14** is a front perspective view thereof; and,
FIG. **15** is a rear perspective view thereof.

The broken lines in the figures represent unclaimed subject matter and form no part of the claimed design. The triangular semiconductor dies is shown broken away in FIGS. **1-15** to indicate that no particular length is claimed.

1 Claim, 15 Drawing Sheets





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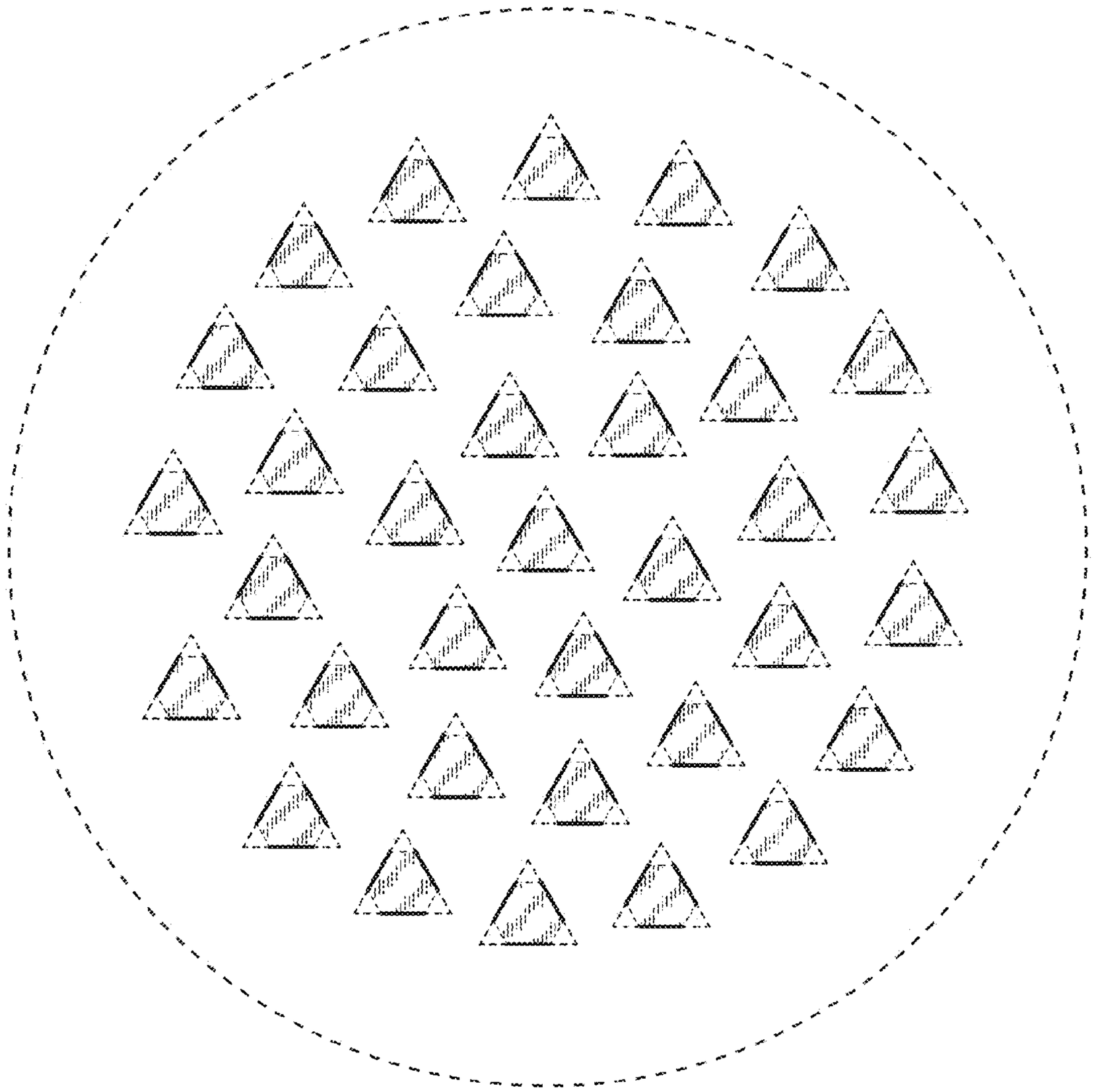

FIG. 1

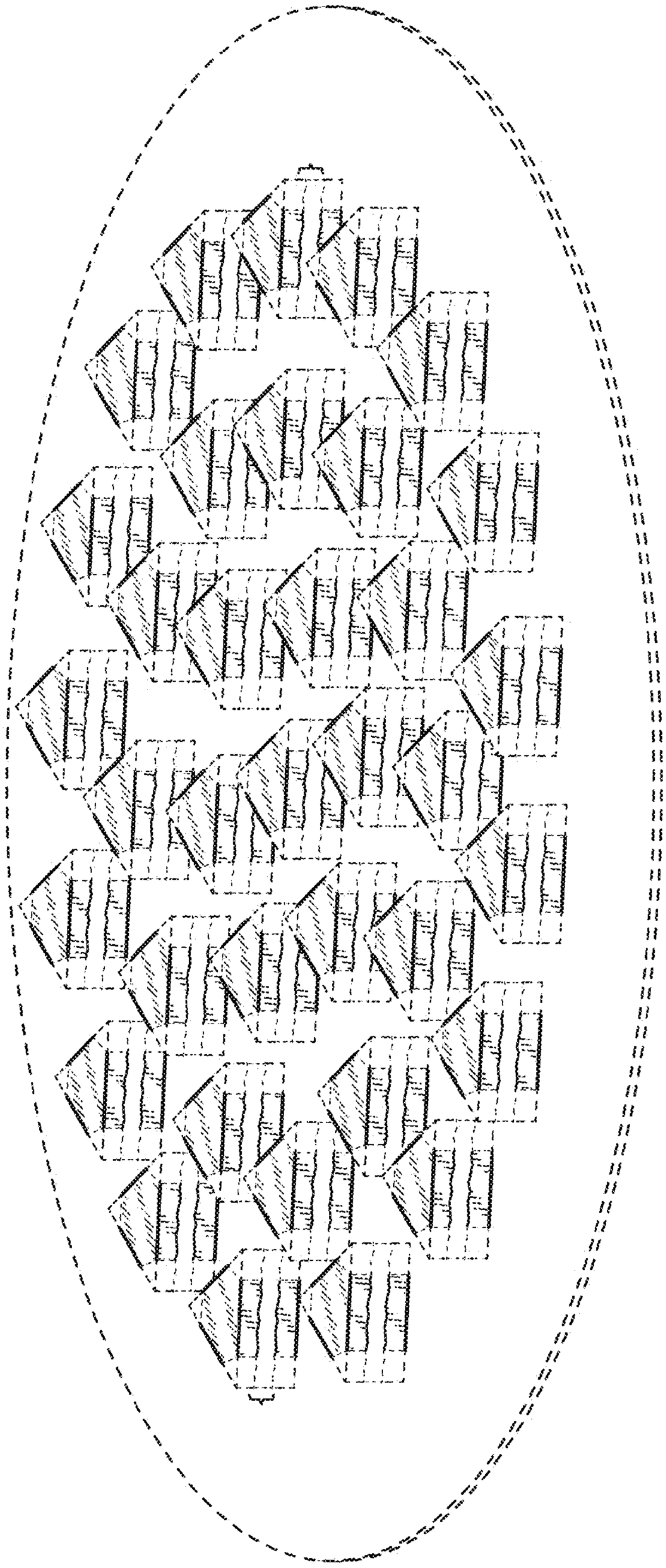

FIG. 2

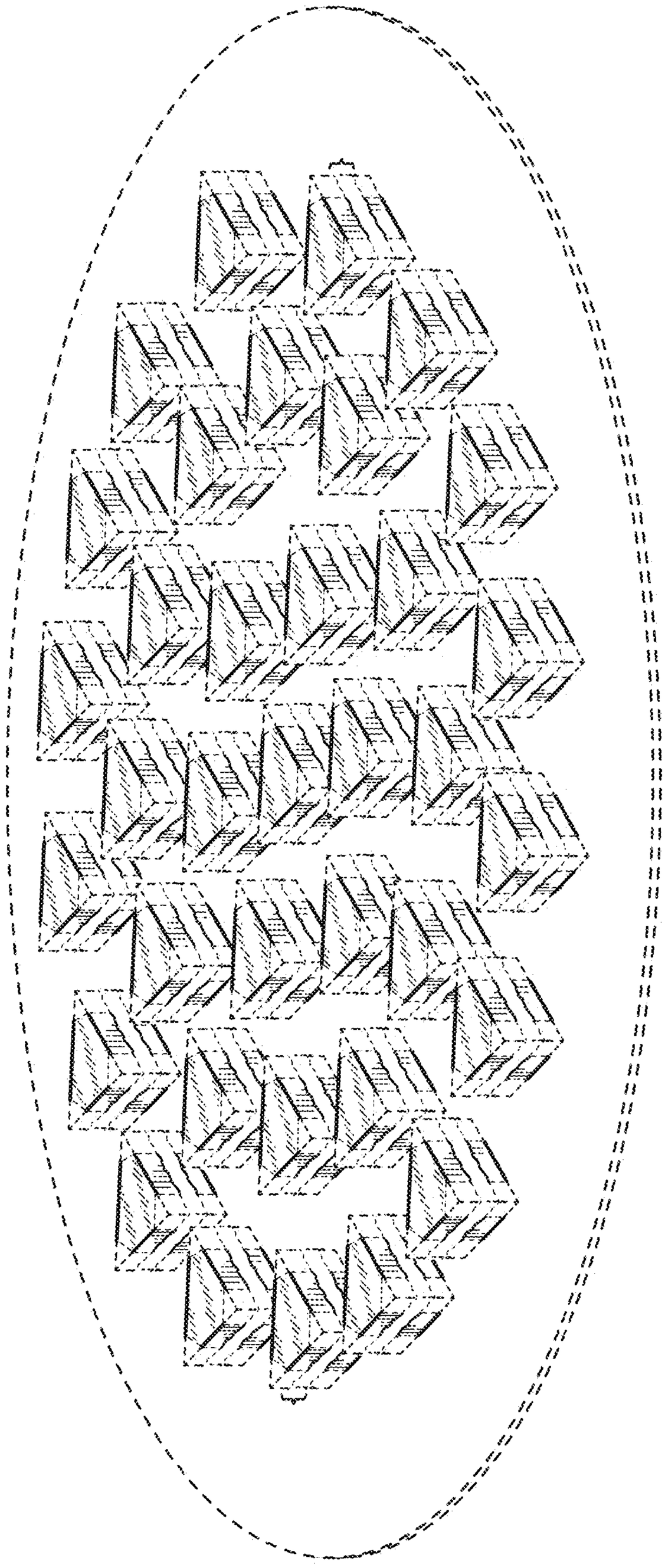

FIG. 3

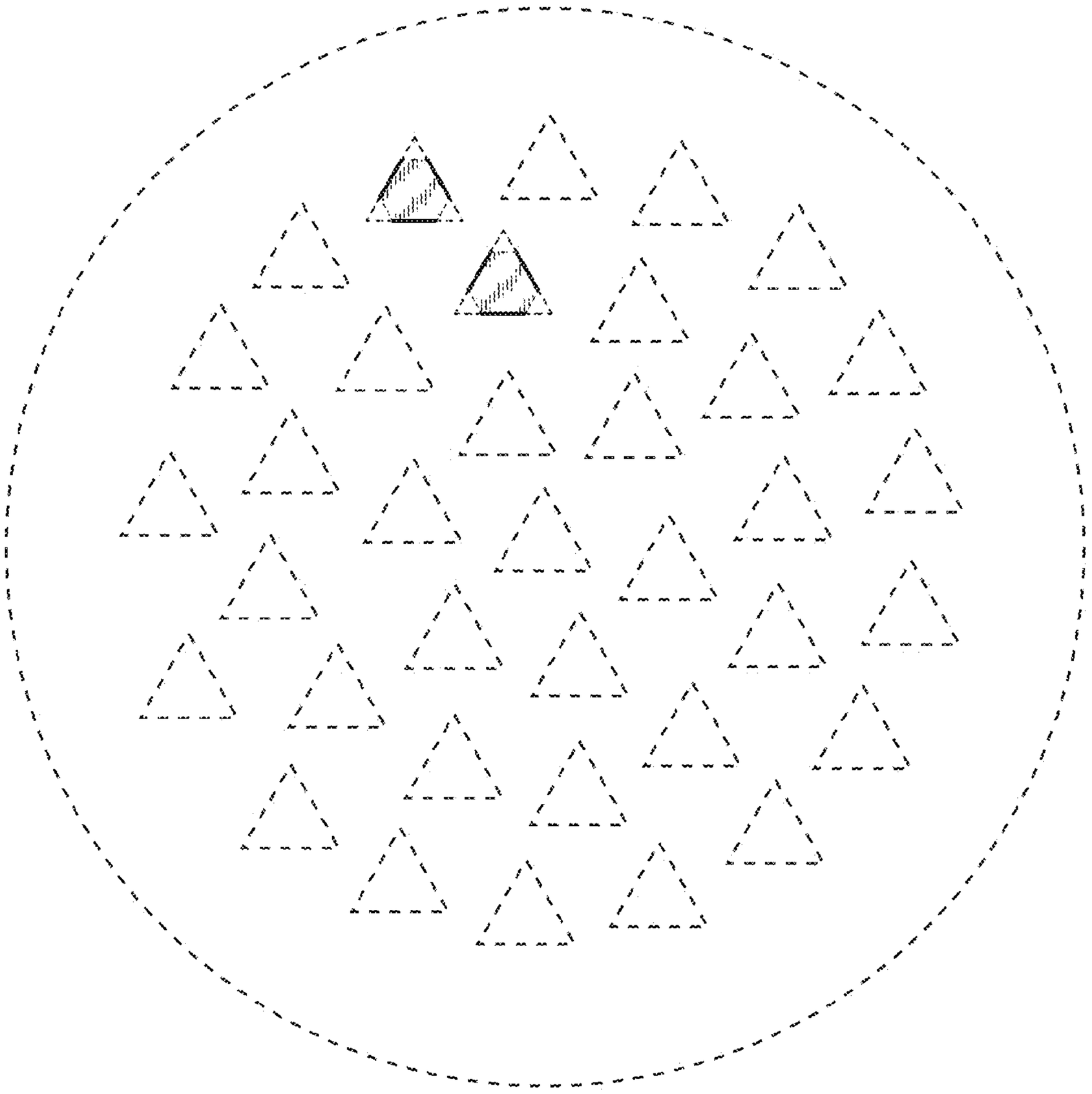

FIG. 4

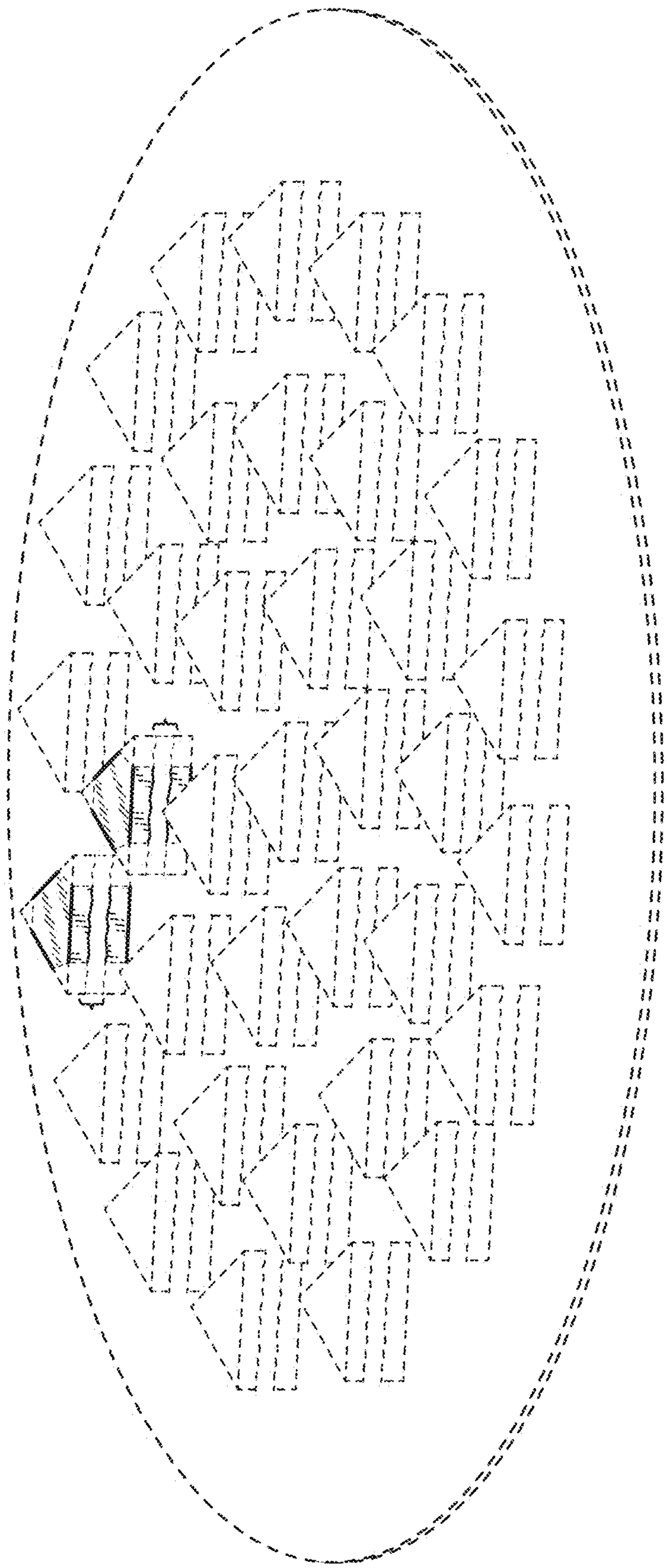

FIG. 5

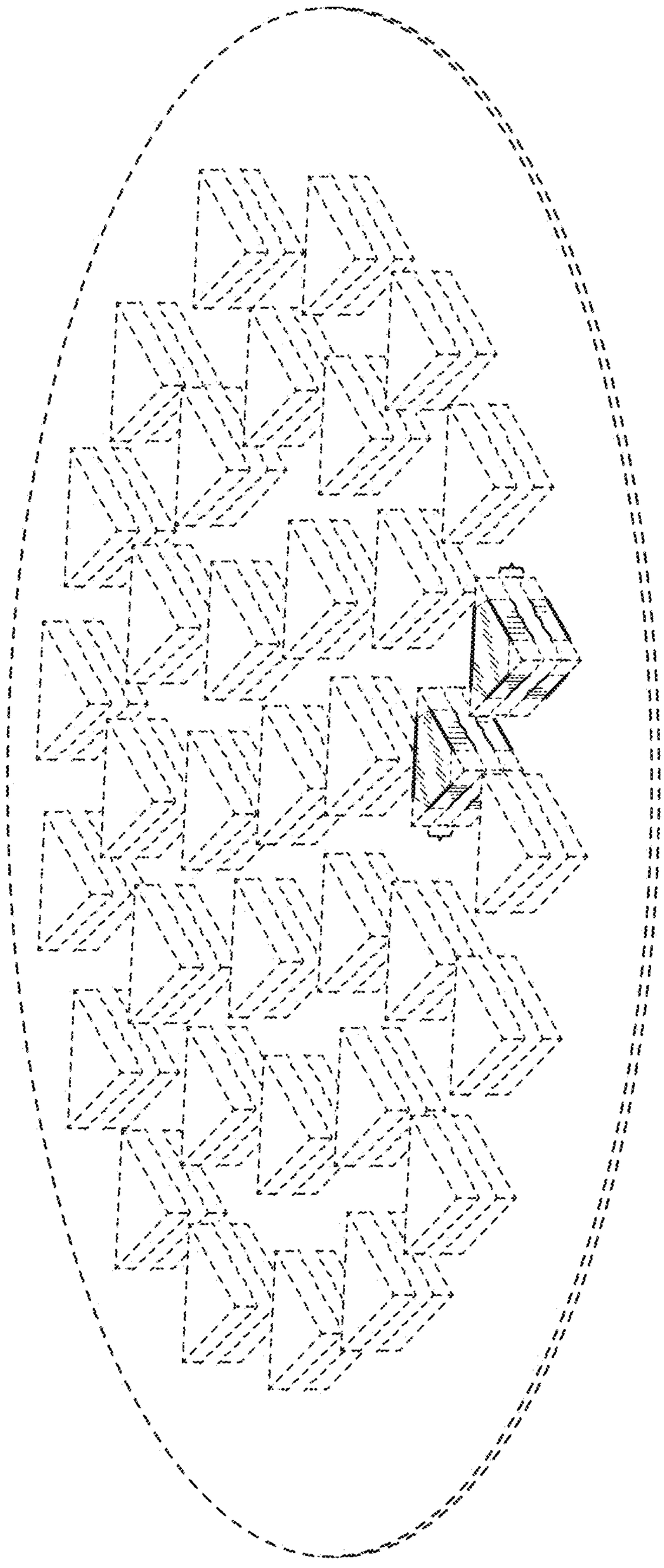

FIG. 6

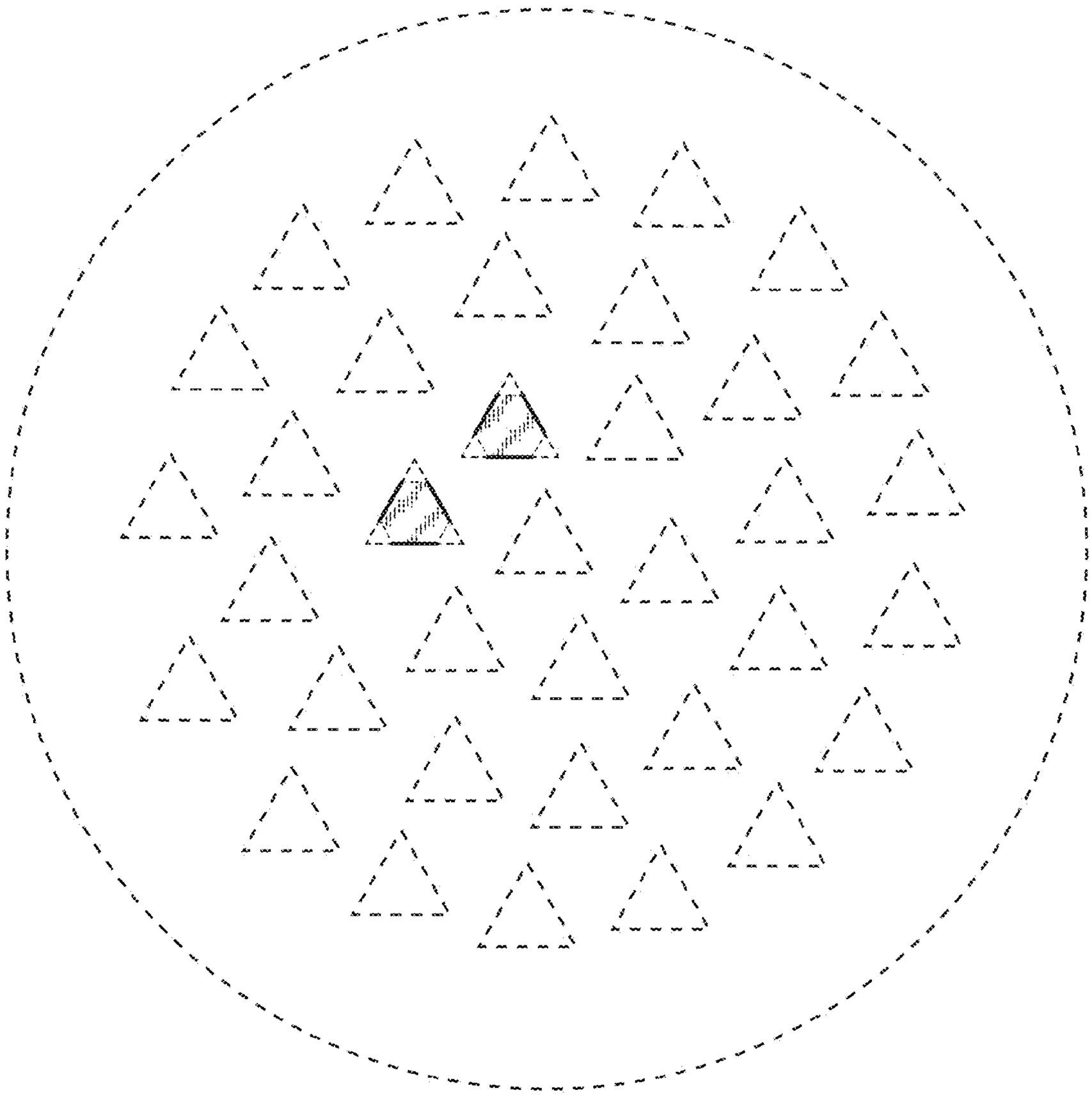

FIG. 7

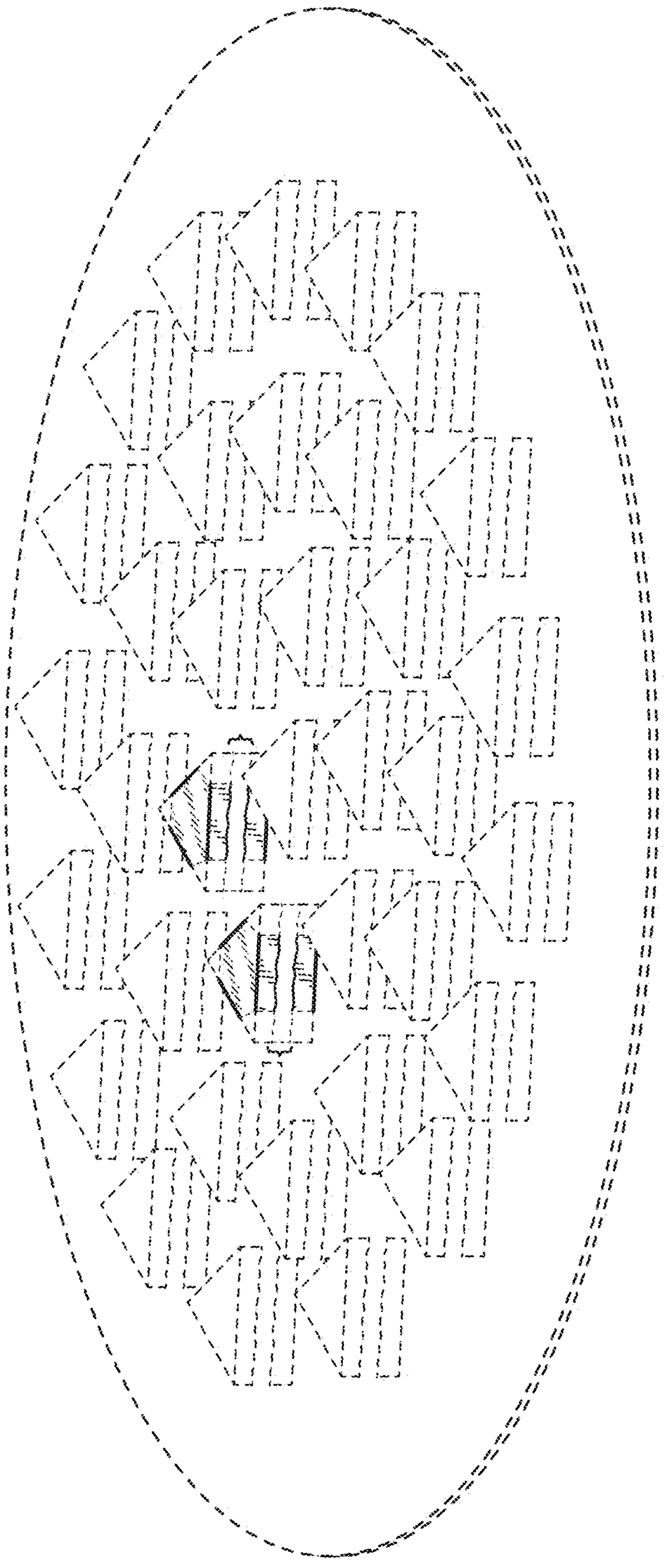

FIG. 8

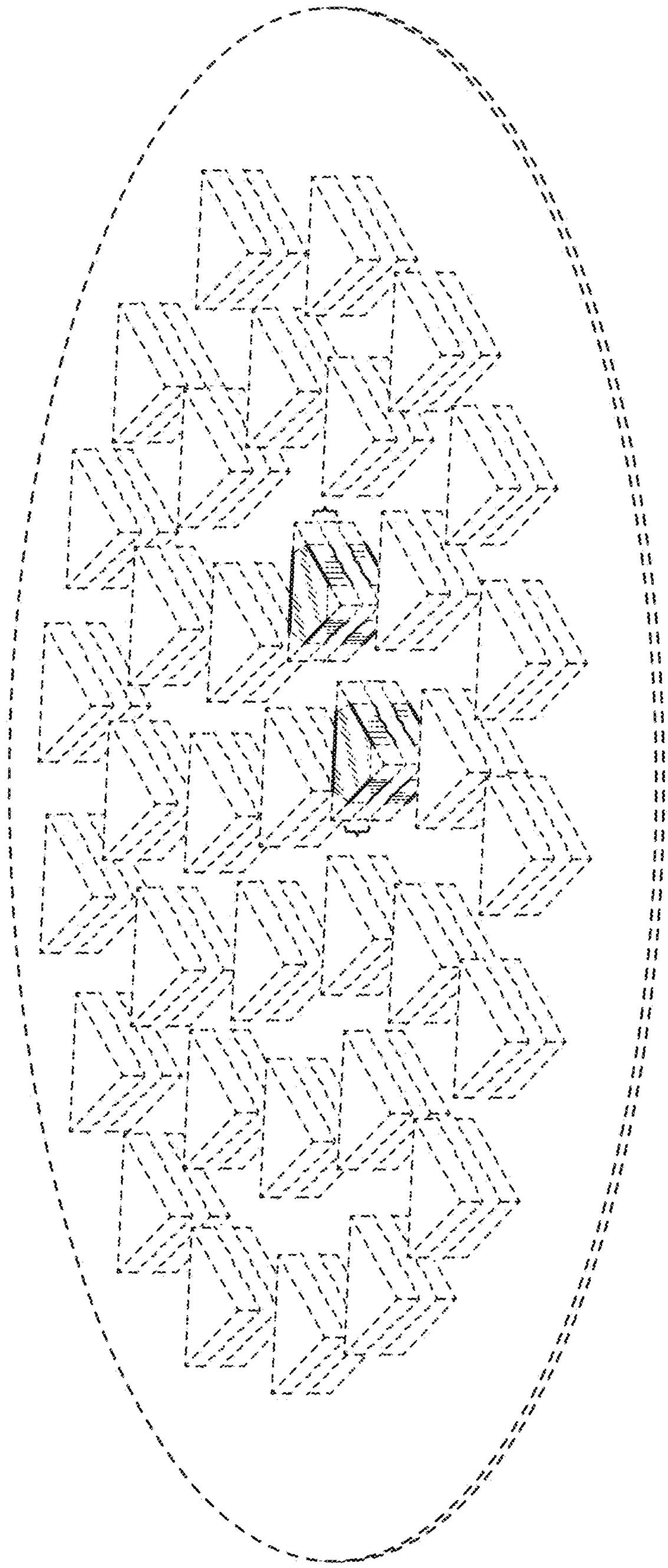

FIG. 9

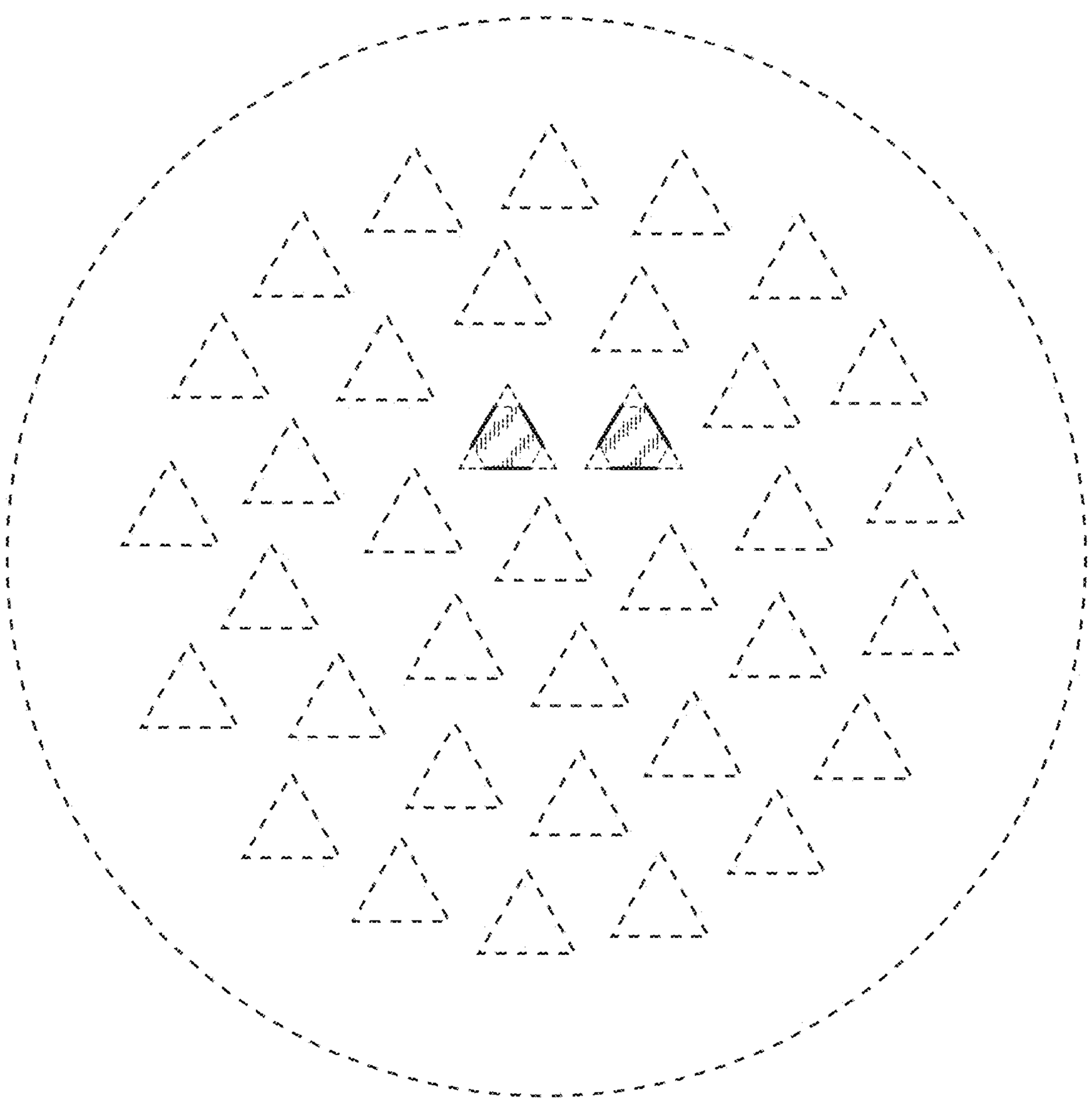

FIG. 10

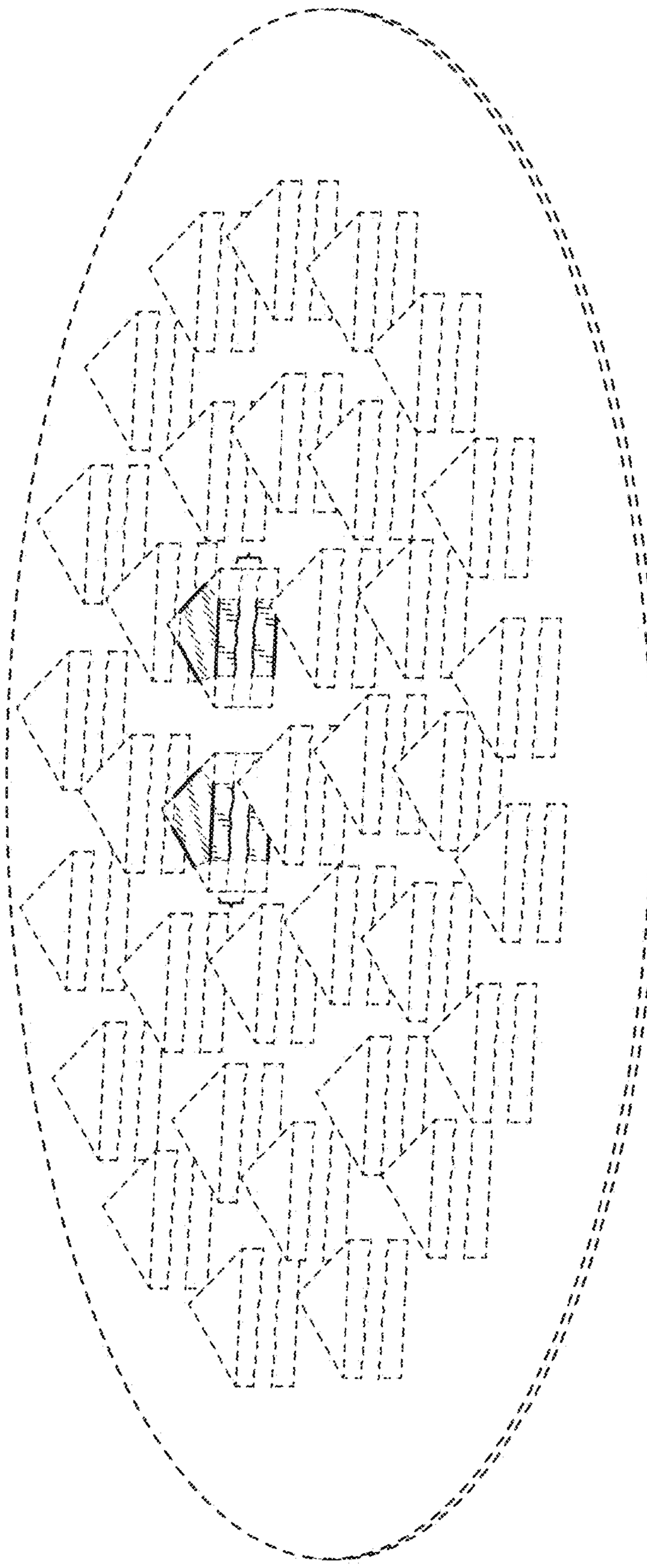

FIG. 11

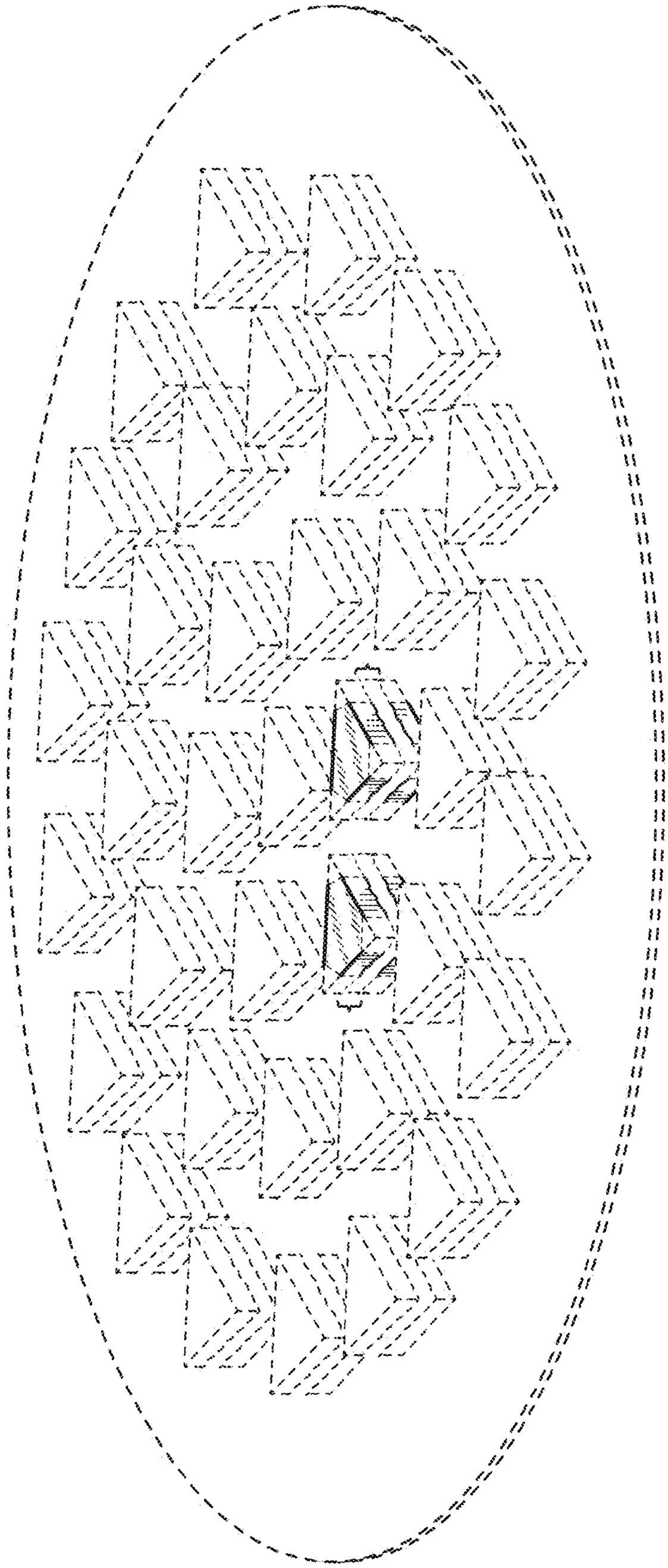

FIG. 12

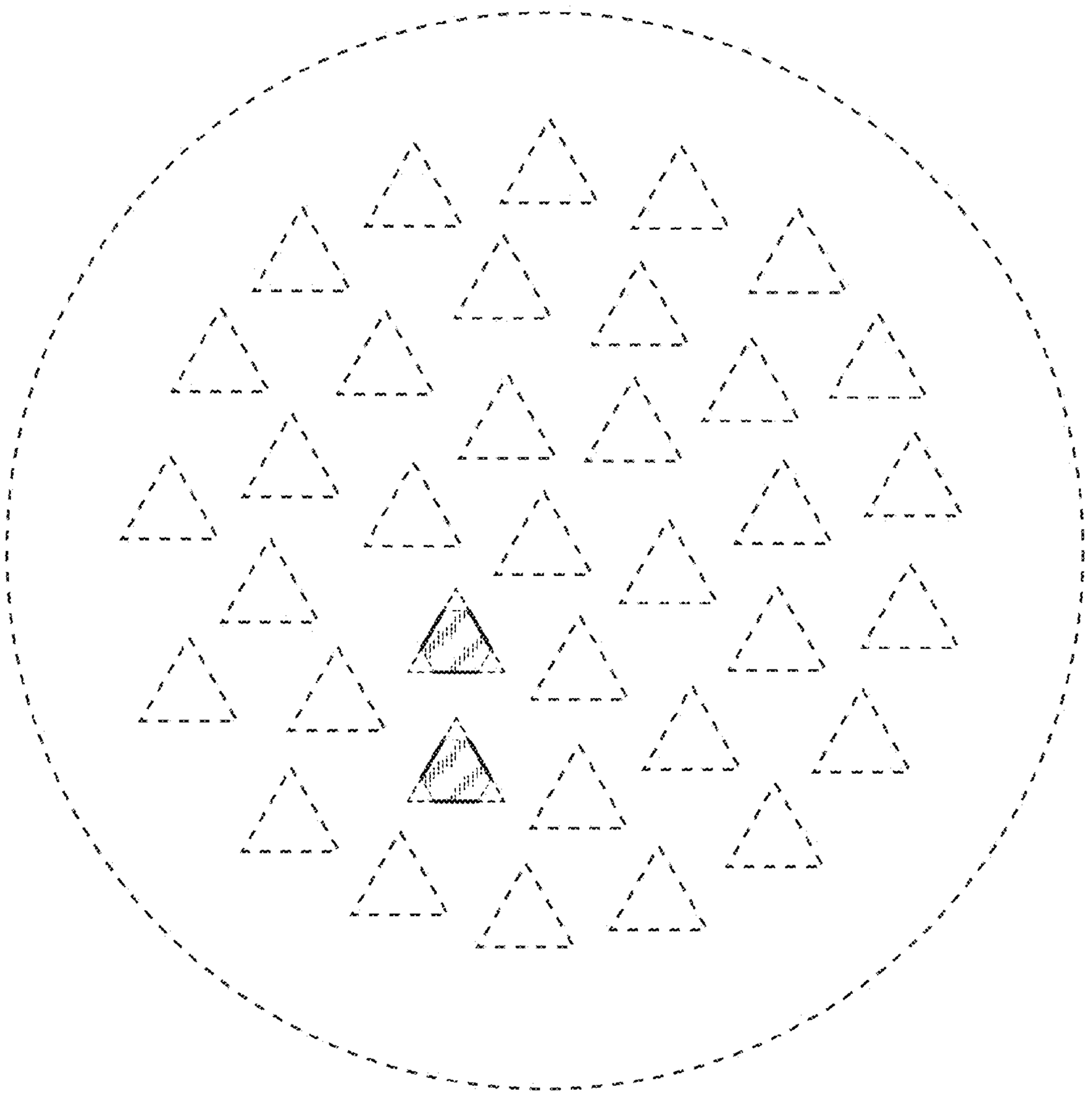

FIG. 13

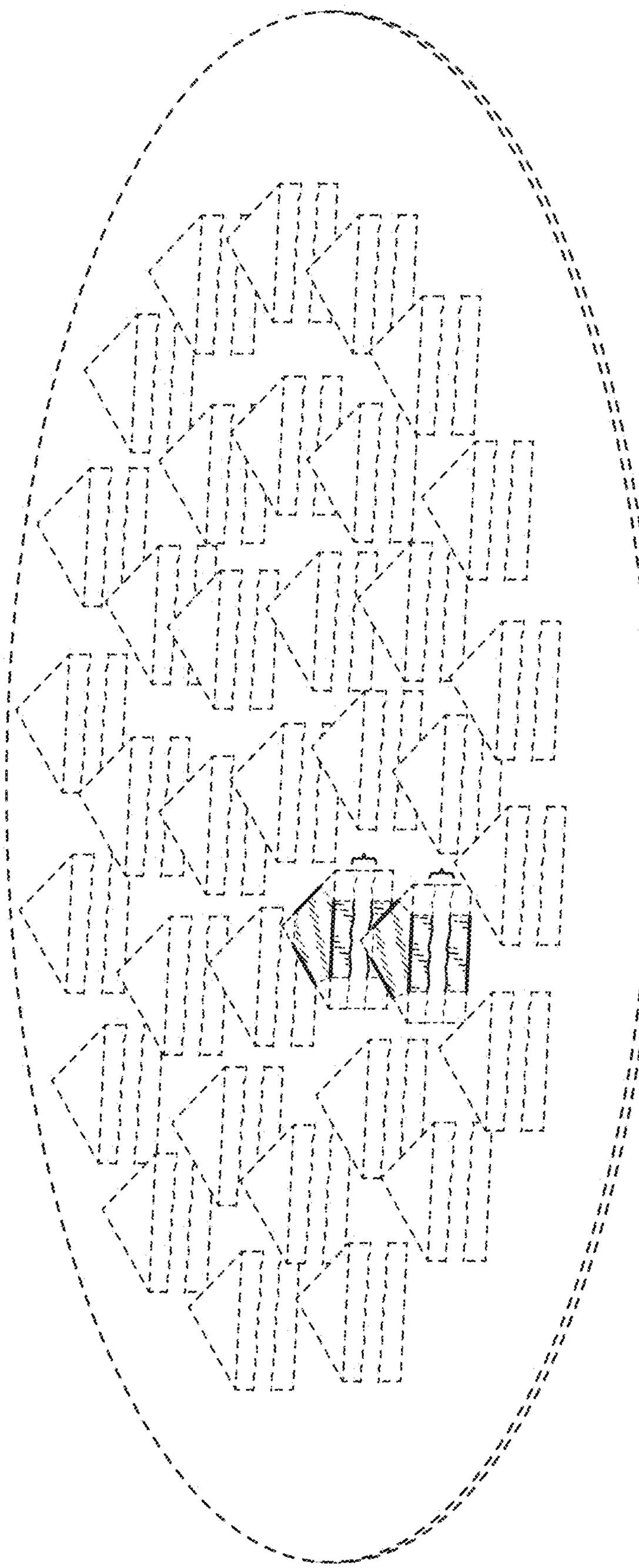

FIG. 14

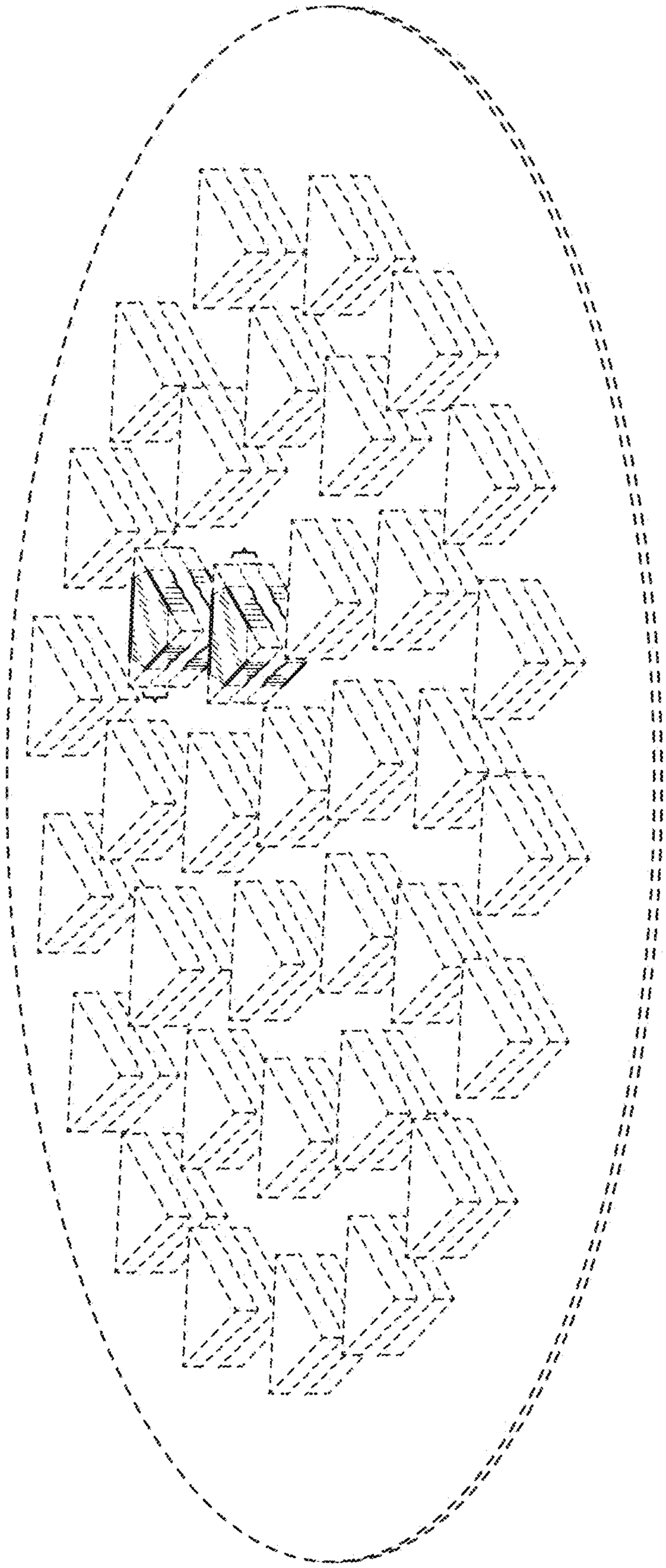

FIG. 15